

Type BMB-R Series

Key Features

- High Impedance at Lower Frequency
- Prevents Signal Ringing
- Wide Frequency Characteristics
- Suited to a Variety of Applications



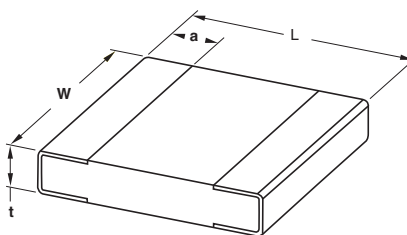
The BMB R Series has been designed for low speed applications and specifically for use in Digital Sound circuitry and similar to prevent ringing. These chip devices have been designed to generate high impedances at low frequencies.

The R series is offered in two sizes 06:03 and 08:05

Specifications

Part Number	Impedance (ohms) at 100MHz (±25%)	DC Resistance (ohms) maximum	Rated Current (mA) maximum
BMB-1J-0080R-S2	80	0.3	200
BMB-1J-0120R-S2	120	0.4	
BMB-1J-0240R-S2	240		
BMB-1J-0300R-S2	300	0.5	
BMB-1J-0600R-S2	600	0.8	
BMB-2A-0080R-S2	80	0.2	300
BMB-2A-0120R-S2	120	0.3	
BMB-2A-0240R-S2	240	0.4	
BMB-2A-0300R-S2	300	0.5	200
BMB-2A-0430R-S2	430		
BMB-2A-0600R-S2	600		

Chip Dimensions

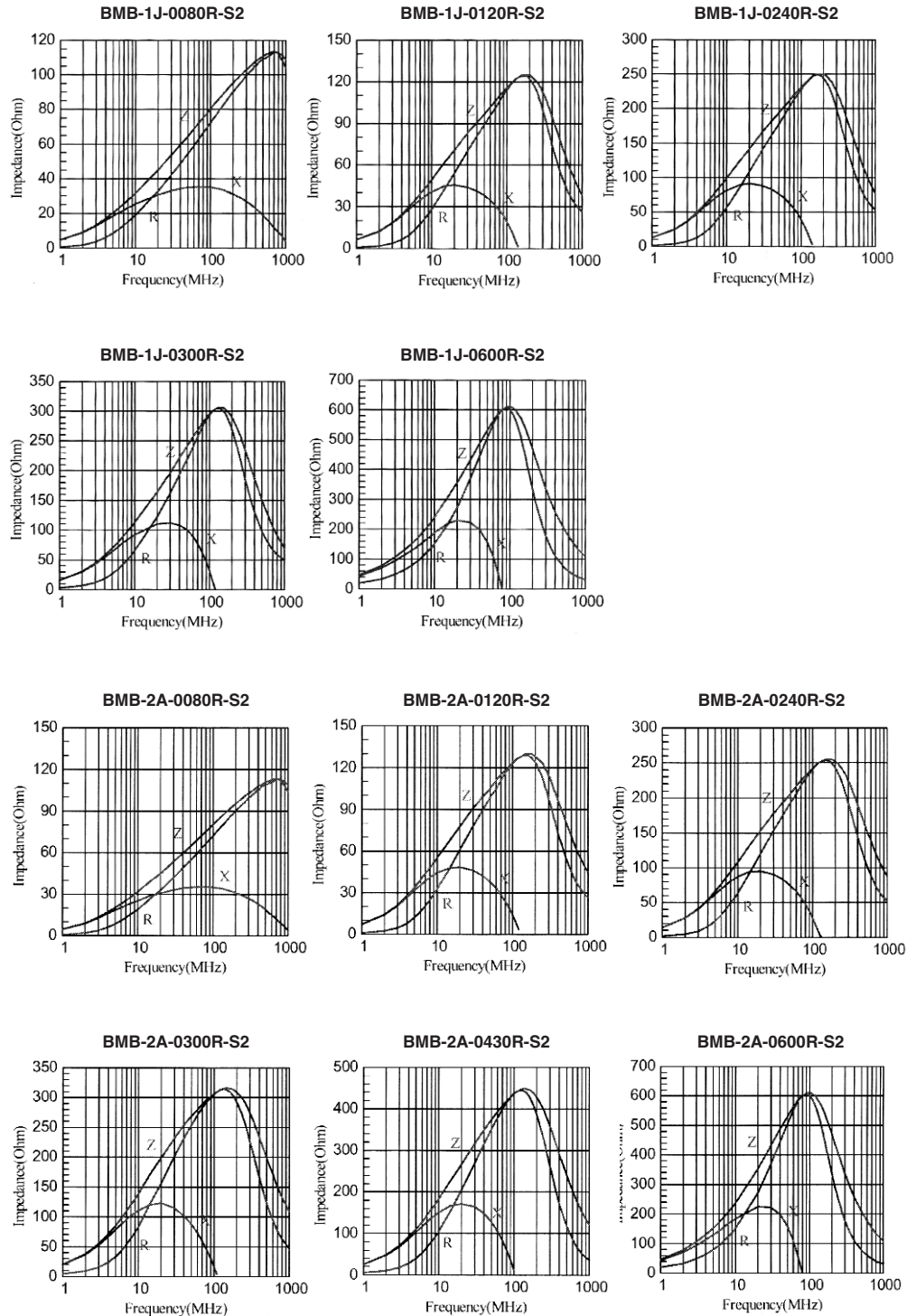


Size	L	W	t	a
0603	1.6 ±0.15	0.8 ±0.15	0.8 ±0.15	0.3 ±0.20
0805	2.0 ±0.20	1.2 ±0.20	0.9 ±0.20	0.5 ±0.30

Operating Temperature Range: -55°C to +125°C

Type BMB-R Series

Characteristic Curves



TE Connectivity, TE connectivity (logo) and TE (logo) are trademarks.

Other logos, product and Company names mentioned herein may be trademarks of their respective owners.

While TE has made every reasonable effort to ensure the accuracy of the information in this datasheet, TE does not guarantee that it is error-free, nor does TE make any other representation, warranty or guarantee that the information is accurate, correct, reliable or current. TE reserves the right to make any adjustments to the information contained herein at any time without notice. TE expressly disclaims all implied warranties regarding the information contained herein, including, but not limited to, any implied warranties of merchantability or fitness for a particular purpose. The dimensions in this datasheet are for reference purposes only and are subject to change without notice. Specifications are subject to change without notice. Consult TE for the latest dimensions and design specifications.